CLAIMS

[Claim 1]

A resin composition comprising:

(A) a thermosetting resin,

(B) one or more selected from the group consisting of a conjugated diene polymer and its derivative, having 2 or more of a functional group including an ethylenically unsaturated bond, and

(C) an inorganic filler whose surface is treated with a silane coupling agent having a functional group including an ethylenically unsaturated bond.

[Claim 2]

The resin composition according to claim 1, wherein the component (A) is one or more selected from the group consisting of a maleimide resin having one or more of an N-substituted maleimide group and a derivative of the said maleimide resin.

[Claim 3]

The resin composition according to claim 1 or 2, wherein the component (B) is a resin having a vinyl group as the functional group including the ethylenically unsaturated bond.

[Claim 4]

The resin composition according to claim 1-3, wherein the silane coupling agent having the functional group including the ethylenically unsaturated bond is a silane coupling agent having a vinyl group or a (meth)acryloyl group as the functional group including the ethylenically unsaturated bond.

[Claim 5]

The resin composition according to claim 1-4, wherein the component (C) is a silica whose surface is treated with the silane coupling agent having the functional group including the ethylenically unsaturated bond.

[Claim 6]

The resin composition according to claim 1-5, wherein the resin composition further comprises (D) a styrene-based thermoplastic resin.

[Claim 7]

The resin composition according to claim 1-6, wherein the resin composition further comprises (E) a curing accelerator.

[Claim 8]

A prepreg comprising the resin composition according to claim 1-7 or a semi-cured product of the resin composition.

[Claim 9]

A laminate comprising a cured product of the resin composition according to claim 1-7 and metal foil.

[Claim 10]

A resin film comprising the resin composition according to claim 1-7 or a semi-cured product of the resin composition.

[Claim 11]

A printed wiring board comprising a cured product of the resin composition according to claim 1-7.

[Claim 12]

A semiconductor package comprising the printed wiring board according to claim 11 and a semiconductor element.